



Material Content Data Sheet



Sales Product Name				ESD202-B1-CSP01005 E6327		Issued		20. July 2018	
MA#				MA001262604					
Package				SG-WLL-2-2		Weight*		0.04 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.039	91.63	91.63	916185	916185	
pad	non noble metal	copper	7440-50-8	0.000	0.00		47		
	inorganic material	silicon	7440-21-3	0.000	0.00		23		
	inorganic material	phosphorus	7723-14-0	0.000	0.13		1328		
	noble metal	gold	7440-57-5	0.000	0.14		1398		
	non noble metal	aluminium	7429-90-5	0.000	0.53		5336		
	noble metal	palladium	7440-05-3	0.000	0.87		8715		
	non noble metal	nickel	7440-02-0	0.003	6.40	8.07	63985	80832	
passivation	inorganic material	SiO2	60676-86-0	0.000	0.11		1072		
	inorganic material	Si3N4	12033-89-5	0.000	0.19	0.30	1911	2983	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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